

**JPCA** Show

53rd International Electronic Circuits Exhibition

**JIEP** Microelectronics Show

38th ADVANCED ELECTRONICS PACKAGING EXHIBITION

**JISSO PROTEC**

25th Jisson Process Technology Exhibition

METaverse DEVICE EXPO  
メタバースデバイス展  
METAVERSE DEVICE EXPO

Connecting Machine to Machine  
**WIRE Japan Show**  
Electrical / Optical Transmission Technology

**Electronics Component & Unit Show**  
JEP Japan Federation of Electronic Parts Distributors and Dealers  
TEA Tokyo Electronics Appliances Wholesalers Association

E-Textile/Wearable

Smart Sensing

無人化ソリューション展

Automated Solution Exhibition

Edge Computing



The Exhibition Guide

# The Total Solution Exhibition for Electronic Equipment 2024

## 2024. 6. 12<sub>Wed.</sub> → 14<sub>Fri.</sub>

### Tokyo Big Sight East Exhibition Halls

Application to Exhibit from: 10:00 am (JST), November 1, 2023



Official Website

**Organizers:** Japan Electronics Packaging and Circuits Association, Japan Institute of Electronics Packaging, Japan Robot Association

**Co-organizers:** Electronic Device Industry News (Sangyo Times, Inc.)  
Electric Wire & Cable News (KOGYO TSUSHIN CO., LTD)  
JTB Communication Design, Inc.  
Japan Federation Of Electronic Parts Distributors and Dealers  
Tokyo Electronics Appliances Wholesalers Association  
SENKEN SHIMBUN CO.,LTD.

**Sponsor (tentative):** Ministry of Economy, Trade and Industry

**Overseas Cooperation:**

World Electronic Circuits Council (WECC) Member Associates:  
China Printed Circuit Association (CPCA), European Institute of Printed Circuits (EIPC),  
Hong Kong Printed Circuit Association (HKPCA), IPC-Association Connecting Electronics Industries (IPC),  
Indian Printed Circuit Association (IPCA), Electronic Industries Association of India (ELCINA),  
Korea Printed Circuit Association (KPCA), Thailand Printed Circuit Association (THPCA),  
Taiwan Printed Circuit Association (TPCA)

Association of Electronic Industries in Singapore (AEIS)  
Korea Packaging Integration Association (KPIA)

As of Oct. 20, 2023

# Come & Look WHAT we can OFFER for ELECTRONICS!!

500 exhibitors (tentative) wait you with cutting edge PCB, Assembly, Equipment, Process Materials and Components.

## Exhibition Outline


<b>Exhibition Period</b>	Wednesday, June 12 to Friday, June 14, 2024, 10:00 a.m. - 5:00 p.m.		
<b>Venue</b>	Tokyo Big Sight East Exhibition Halls	<b>Managed by</b>	Japan Electronics Packaging and Circuits Association (JPCA)
<b>Admission</b>	1,000 Yen (including tax) * Free Admission for those who have pre-registered online.	<b>Secretariat Office</b>	JTB Communication Design, Inc.

## Attractive Seminar Programs/Events

PCB, Assembly, PCB Related Equipment, Materials/Processes, High-speed Transmission Technology for Autonomous Driving, High-current Technology for EVs, Advanced Packaging Technology, Materials and Process Technology for Power Semiconductors/Glass Substrates, Low-emission Technology for Climate Change, E-Textile/Wearable Technology, Sensor & Sensing Technology, Automated Technology/Solutions, Edge Computing, On-Device technology, etc.

## Exhibitions held inside the exhibition/relevant exhibits

Electronic circuits technology	High-density packaging technologies	Electronic Component Packaging Technologies
 <p><b>JPCA Show</b> 53rd International Electronic Circuits Exhibition</p> <ul style="list-style-type: none"> <li>● <b>PWB Tech</b> Products and Technologies related to electronic circuit boards (Design &amp; Simulation, Reliability &amp; Inspection, Circuit Board Materials, Functional &amp; Process Materials, Manufacturing equipment, Related Systems), etc.</li> <li>● <b>Module JAPAN</b> Module board / Module Board mounting / Embedded Component Board, General technology for built-in parts (Design &amp; Simulation, Reliability &amp; Inspection, Circuit Board Materials, Functional &amp; Process Materials, Manufacturing equipment, Related Systems), etc.</li> <li>● <b>Flexible Printed Circuits Products Area</b> General technology for Flexible Printed Circuits (Design &amp; Simulation, Reliability &amp; Inspection, Circuit Board Materials, Functional &amp; Process Materials, Manufacturing equipment, Related Systems)</li> <li>● <b>EMS Japan</b> Services and technologies related to EMS, ODM and contract manufacturing of semiconductors (Design &amp; Simulation, Reliability &amp; Inspection, Circuit Board Materials, Functional &amp; Process Materials, Manufacturing equipment, Related Systems)</li> </ul> <p><b>Organizer:</b> Japan Electronics Packaging and Circuits Association</p>	 <p><b>JIEP Microelectronics Show</b> 38th ADVANCED ELECTRONICS PACKAGING EXHIBITION</p> <p>General technology for implementation and electric technology (Materials / Circuit and Mounting design / High speed high frequency / Electromagnetic properties / Electronic parts / mounting / Optical circuit mounting / Environmental affinity implementation / Semiconductor Package / Micro mechatronics mounting technology / Related Manufacturing equipment)</p> <p><b>Organizer:</b> Japan Institute of Electronics Packaging</p>	 <p><b>JISSO PROTEC</b> 25th Jisso Process Technology Exhibition</p> <ul style="list-style-type: none"> <li>■ Electronic Component Placement Machines and related Equipment and Systems: electronic component placement machines (Mounter), electronic component insertion machines (Inserter), screen printers, soldering equipment (reflow oven), and dispensers</li> <li>■ Packaging related Equipment and Systems: transfer systems, AGV, automatic warehouse, taping machines and materials, bulk feeders and other feeders, and automatic assembly machines, laser marking machine, cleaning equipment - cleaner</li> <li>■ Semiconductor Packaging Machines and Systems: bonding equipment, flip chip packaging systems, COB systems</li> <li>■ Industrial Robotics: handling robots, assembly robots, transport robots</li> <li>■ Inspection/Test Equipment: automated optical inspection equipment, inspection/measuring equipment associated with semiconductor manufacturing</li> <li>■ Packaging Design Systems: design tools, production optimizing software, and packaging programming equipment</li> <li>■ Packaging Device Packaging Materials</li> <li>■ Packaging Joining Systems - Solder/joining materials</li> <li>■ High Frequency Compatible Devices, Components, and Materials</li> <li>■ Environment related Devices and Materials</li> </ul> <p><b>Organizer:</b> Japan Robot Association</p>

METaverse DEVICE EXPO	Electrical/optical transmission technology	Semiconductors and Electronic parts	Highly functional textile
 <p><b>METaverse DEVICE EXPO</b></p> <p>Products and technologies related to the metaverse (Semiconductor (Processor, Memory, Sensor), AR • VR • MR/goggle / Display (micro LED • OLED) / Camera/ Headset/Controller/Cooling device etc)</p> <p><b>Co-organizers:</b> Japan Electronics Packaging and Circuits Association, Electronic Device Industry News (Sangyo Times, Inc.)</p>	 <p><b>Connecting Machine to Machine</b> <b>WIRE Japan Show</b></p> <p>Electrical / Optical Transmission Technology</p> <p>General transmission technology for using wire and cable (Industrial equipment / Electrical wire, cable and connector / Electric wire processing machine / Wiring material / Wire Harness / Measuring instrument for electric wire and cable / Various devices + D116 / Inspection technology / M2M transmission / Optical transmission)</p> <p><b>Co-organizers:</b> Japan Electronics Packaging and Circuits Association, Cable News (KOGYO TSUSHIN CO., LTD)</p>	 <p><b>Electronics Component &amp; Unit Show</b></p> <p>JEPF Japan Federation Of Electronic Parts Distributors And Dealers TEA Tokyo Electronics Appliances Wholesalers Association</p> <p>General technology for solutions by Semiconductors and Electronic parts (Semiconductors / Electronic Devices / Sensors / Mechanical Devices / FA control equipments / Measuring instruments / Power Sources / IoT and M2M Solution / Manufacturing solution system)</p> <p><b>Co-organizers:</b> Japan Federation Of Electronic Parts Distributors And Dealers, Tokyo Electronics Appliances Wholesalers Association</p>	 <p><b>E-Textile/Wearable</b></p> <p>A mix e-textile of electronic technology, fiber and clothing (General technology for smart textile, stretchable and wearable (Textile material / Conductive material / material / Knitting / weaving technology / Print marking technology / Films)</p> <p><b>Co-organizers:</b> Japan Electronics Packaging and Circuits Association, SENKEN SHIMBUN CO., LTD.</p>

Sensor technology	Automated technology/Automated Solution	Edge solution technology
 <p><b>Smart Sensing</b></p> <p>General technology for Sensor and Sensing System (Sensors, Sensor Nodes, Semiconductors, Parts and Devices, Electronics, Telecommunications Devices, Network Systems, Software, Data Platform, Power Sources, Other Related Devices, Technologies and Services)</p> <p><b>Co-organizers:</b> Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p>	 <p><b>Automated Solution Exhibition</b></p> <p>Automated technology / Automated Solution, Monitoring system / Remote control system / ADAS/Deep learning / Noncontact system / Touchless system / AR/Anomaly detection system / facial recognition system / AI etc.</p> <p><b>Co-organizers:</b> Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p>	 <p><b>Edge Computing</b></p> <p>Advantageous general edge solutions for areas such as low delay, high safety and low communication volume [Edge Application Areas] Automatic operation system / Factory Automation / Telemedicine / AR/VR / Smart city / Agritech / FinTech / Unmanned store, etc.</p> <p><b>Co-organizers:</b> Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p>

**NEW Application zones** If you wish to exhibit in the Application Zone, please select the zone when applying to exhibit.

<b>Automated Driving</b> High-speed Transmission Technology Zone for Automated Driving	<b>EV (electric vehicle)</b> High Current Technology Zone for EV	<b>Power Semiconductor/Glass Substrates</b> Materials and Process Technology Zone for Power Semiconductors / Glass Substrates
<b>Advanced Packaging</b> Advanced Semiconductor Packaging Technologies Zone for Chiplets, etc.	<b>Climate Change Solutions</b> Low Emission Technology Zone Contributing to Climate Change Mitigation	

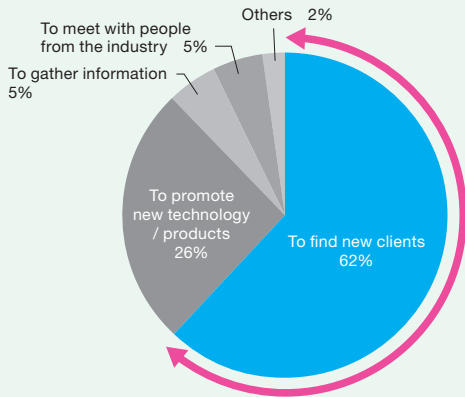
**Venue** Tokyo Big Sight East Exhibition Halls

**Exhibit scale** 517 companies / 1,273 booths

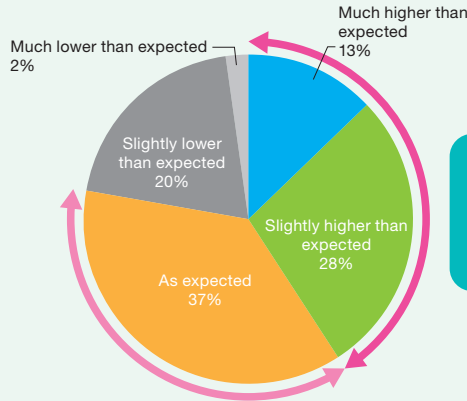
**Number of visitors** 48,018 people

Exhibitors Questionnaire

1. Reasons for exhibiting

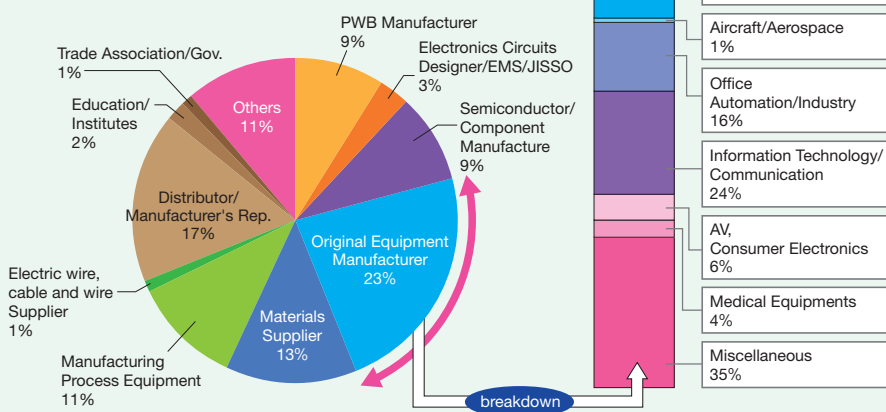


2. Effects of exhibiting



Exhibited for the purpose of developing new customers, 41% of exhibitors exceeded expectations, 78% of exhibitors exceeded expectations.

Industry Classification of Visitors



Not limited to traditional electronics and electrical equipment manufacturing visitors, networking with visitors from new application fields is expected. networking with visitors from new application fields is expected.

**attention** Providing new networking opportunities!

Exhibitor Networking Meetings will be held to promote networking among exhibitors!

"Student Welcome Booth" and "Exchange Plaza for Students" will be set up to welcome young generation that will be responsible for tomorrow's electronics!

Expected VISITORS

Visitors from a wide variety of industries and Sectors!

Semiconductors, Telecommunications, Mobility (Automobiles, Motorcycles, Bicycles), Shipping, Trains, Aircraft, Agriculture, Transportation Infrastructure, Logistics, Gaming and Toys, Metaverse, AI, AR/VR, Forestry, Fisheries, Food, Education, Medical, Apparel/Sports Equipment, Finance, Local Government, Beauty, Smart Home Appliances, Defense Equipment, e-Sports, AV, Drones, Wearable Devices, Sensors, Disaster Prevention, Robotics, Biometrics, Energy, Dx/Gx/Cx/Sx, Tourism Dx, Signage, SmartX, etc.

- AGC / AmkorTechnology / CKD / DIC / HUAWEI / JA-group / JFE Group / East Japan Railway Company Group / JSR / JTB / JVCKENWOOD / KDDI Group / LG Group / LIXIL / NEC Group / NHK Technologies / NTN / NTT Group / Rapidus / SK Group / SMBC Group / SUBARU / SUMCO / TDK / THK / TOTO / TSMC Group / YKK / AISIN Group / ASAHI SOFT DRINKS / AEON Group / Intel / OKAMURA / OMRON Group / Olympus / CASIO COMPUTER / National Research Council of Canada / KANSAI ELECTRIC POWER Group / Canon / KINDEN / KUBOTA / CITIZEN WATCH Group / Sharp / Shachihata / Seiko Watch / ZEON / SECOM / Sony Group / SoftBank / Tiger / DUSKIN / Terumo / Television Saitama / TV TOKYO / Deloitte Tohmatsu Consulting / DENSO Group / TOENEC / TOYOTA MOTOR / TOYOTA AUTO BODY / NIKON / NIPRO Group / NORITAKE / PARK24 / HASEKO Group / Panasonic Group / HIROSE ELECTRIC / Foster Electric / BROTHER INDUSTRIES / Bridgestone Group / Hosiden / MISAWA HOMES / Mizuho Financial Group / Yamaha / Ricoh / Resona Group / Rinnai / Resonac / Lenovo Japan / ROHM Group / Aisan Industry / Aichi Steel / Asahi Kasei / Yaskawa Manufacturing / ITOCHU / Japan Aerospace Exploration Agency / Yokogawa Electric / The Bank of Yokohama / YOKOHAMA National University / KAGA ELECTRONICS / Marubeni / Iwatani / KYOCERA / KYUSHU UNIVERSITY / Kyushu Electric Power / Keio University / KANEMATSU / Furukawa Electric / TODA / KURODA ELECTRIC / Mitsui Chemicals / MUFG Bank / MITSUBISHI MOTORS / Mitsubishi / Mitsubishi Research Institute / Mitsubishi Electric / Sanwa Shutter / National Institute of Advanced Industrial Science and Technology / Shiseido / Kagoshima Prefecture / SUMITOMO / Sumitomo Wiring Systems / Idemitsu Kosan / The Shoko Chukin Bank / KOITO MANUFACTURING / Komori Corporation / MORINAGA MILK INDUSTRY / SHIMIZU / Kawasaki Heavy Industries / Kurabo Industries / Waseda University / SOHGO SECURITY SERVICES / Murata Manufacturing / TAIYO YUDEN / Osaka Research Institute of Industrial Science and Technology / OSAKA UNIVERSITY / Dai Nippon Printing / OBAYASHI / DAIWA HOUSE INDUSTRY / TEIJIN / SHIMADZU / Toray Industries / TOKAI RIKI / Tokyo Electron / TOKYO GAS / Tokyo Fire Department / The University of Tokyo / Tokyo Metro / TOSHIBA GROUP / TOHOKU UNIVERSITY / TOYOBOS / Nanya Group / NICHIA / Nissan Motor / Nitto Boseki / IBM / Samsung C&T Japan / Texas Instruments Japan / Honeywell Japan / Nikkei / NIHON TOYO / Japan Radio / Hitachi Zosen / National Agriculture and Food Research Organization / Fuji Chimera Research Institute / FUJI SOFT / FUJIFILM Group / Fujitsu Group / Toyoda Gosei / TOYOTA INDUSTRIES / Honda Motor / MEIDENSHA / Nomura Research Institute / Nomura Securities / Yazaki / Yano Research Institute (in no particular order)

Overseas Visitors: from 27 countries/regions

## Exhibition Fee

Category	1 booth/9m <sup>2</sup> *Tax included
Non-Members	Yen 496,100
Members <sup>*1</sup>	Yen 423,500

\*1 Members of the following associations

WECC Member Associations (OPCA, EIPC, ELCINA, HKPCA, IPC, IPCA, KPCA, THPCA, TPCA)  
AEIS, KPIA

\* Size of a booth is 9m<sup>2</sup> (3m × 3m).

\* Fee is for raw space only, Booth construction, cleaning, electricity, water supply, etc. are not included in the exhibition fee.

## How to apply (From November 1, 2023 (Wed.) 10:00a.m (JST))

Please apply online on our website. ([www.jpccashow.com](http://www.jpccashow.com))

If you use the Application Form, please apply by e-mail or FAX.

Please select the exhibition based on your products, technologies or services and carefully read the "Exhibition Regulations" on the back of the Application Form.

For the exhibition which has the exclusive application form, the relevant exhibition regulations shall be applied.

An invoice will be issued upon receipt of your application.

Please download the invoice from each exhibitor's website.

## Application Deadline

**Thursday, February 29, 2024**

**If all spaces are reserved before the deadline, the application will no longer be accepted.**

## Cancellation charges

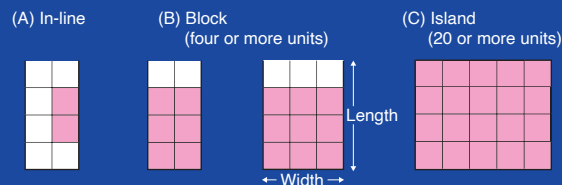
If an exhibit is cancelled to suit the exhibitor's circumstances, cancellation charges (full or partial fees) shall apply as below.

Date of receipt of written notice of cancellation	Cancellation charges
Until Thursday, February 29, 2024	30% of booth fees
Friday, March 1 - Sunday, March 31, 2024	50% of booth fees
Monday, April 1 - Tuesday, April 30, 2024	70% of booth fees
From Wednesday, May 1, 2024 onward	100% of booth fees

## Schedule prior to the Exhibition (Tentative)

2023 November	2024 February	March	April	May	June
▲ November 1 (Wed.) 10:00 – Start of Exhibition Application	▲ February 29 (Thur.) Exhibitor application deadline	▲ Mid-March Exhibitor Manual available  ▲ Late March Booth Location Selection Meeting	▲ Mid-April Sending Invitations Visitor Registration begins		▲ June 10 (Mon.) - 11 (Tue.) Installation period  ▲ June 12 (Wed.) - June 14 (Fri.) Exhibition open  * Immediate removal on the last day
← Mid-March onwards Submission of necessary forms →					

## Booth type



\* In some cases, it may not be possible to prepare the requested booth type.

## Assignment of Booth Locations

**Booths will be assigned at the Booth Location Selection Meeting (Scheduled to be held in late March 2024).**

As a rule, exhibitors will be able to choose their booth locations on a first-come-first-served basis.

\* For details, please refer to the Exhibitor Rules and Regulations.

## Exhibitor Support Program Option

Promotion services will provide an opportunity to increase your presence at the exhibition.

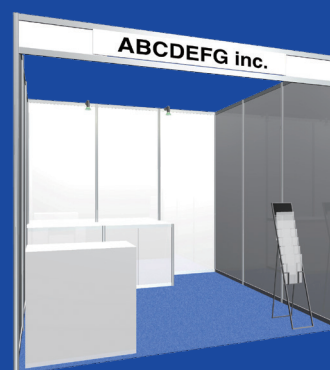
## Package booth Option

### ● 1 booth / basic plan

Price: 118,800 Yen (Tax included)

This plan includes the minimum necessary booth fixtures and fittings, power supply and carpet.

For more details, please refer to the document to be distributed around mid-March 2024.



Managed by

**Japan Electronics Packaging and Circuits Association (JPCA)**

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Official Website